- EPICTM (Enhanced-Performance Implanted CMOS) Submicron Process
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
- 2000-V Human-Body Model (A114-A)
- 200-V Machine Model (A115-A)
- 1000-V Charged-Device Model (C101)
- Package Options Include Plastic Small-Outline (DW), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

(TOP VIEW)									
OE [1	O_{20}]v _{cc}						
1Q [2	19] 8Q						
1D [3	18] 8D						
2D [4	17]7D						
2Q [5	16] 7Q						
3Q [6	15] 6Q						
3D [7	14] 6D						
4D [8	13] 5D						
4Q [9	12] 5Q						
GND [10	11] CLK						

DGV, DW, OR PW PACKAGE

description

This octal edge-triggered D-type flip-flop is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH374 is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH374 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each flip-flop)								
	INPUTS	OUTPUT						
OE	CLK	D	Q					
L	\uparrow	Н	Н					
L	\uparrow	L	L					
L	H or L	Х	Q ₀					
н	Х	Х	Z					



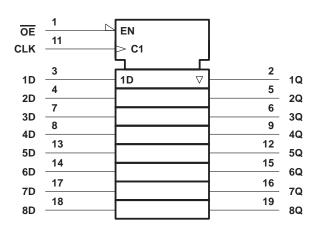
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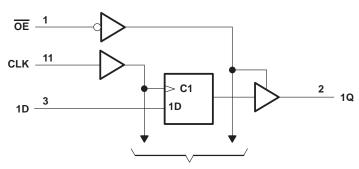


logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Output voltage range, V_O (see Notes 1 and 2) Input clamp current, I_{IK} ($V_I < 0$) Output clamp current, I_{OK} ($V_O < 0$) Continuous output current, I_O Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 3):	· · · · · · · · · · · · · · · · · · ·	-0.5 V to 4.6 V 0.5 V to V _{CC} + 0.5 V 50 mA 50 mA
Package therman impedance, AJA (see Note 3).	DW package PW package	58°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 4.6 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage		1.65	3.6	V	
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
VIH	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 V \text{ to } 3.6 V$	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
VIL	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
VI	Input voltage		0	VCC	V	
Vo	Output voltage		0	VCC	V	
		V _{CC} = 1.65 V		-4		
1.		V _{CC} = 2.3 V		-12		
ЮН	Hign-level output current	V _{CC} = 2.7 V		-12	mA	
	VIL Low-level input voltage VI Input voltage VO Output voltage IOH High-level output current IOL Low-level output current At/Δv Input transition rise or fall rate	V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
1.		V _{CC} = 2.3 V		12		
'OL	Low-level output current	V _{CC} = 2.7 V		12	mA	
		V _{CC} = 3 V		24	1	
$\Delta t/\Delta v$	Input transition rise or fall rate	•		5	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics	over	recommended	operating	free-air	temperature	range	(unless
otherwise noted)					-	•	

PA	RAMETER	TEST CONDITIONS	VCC	MIN	TYP†	MAX	UNIT
		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} -0.	2		
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
		$I_{OH} = -6 \text{ mA}$	2.3 V	2			
VOH			2.3 V	1.7			V
		$I_{OH} = -12 \text{ mA}$	2.7 V	2.2			
			3 V	2.4			
		$I_{OH} = -24 \text{ mA}$	3 V	2			
		I _{OL} = 100 μA	1.65 V to 3.6 V			0.2	
		I _{OL} = 4 mA	1.65 V			0.45	
\/~.		I _{OL} = 6 mA	2.3 V			0.4	v
V _{OL} I _{OL} = 12 mA		40	2.3 V			0.7	V
		IOL = 12 mA	2.7 V				
		I _{OL} = 24 mA	3 V			0.55	
Ιį		V _I = V _{CC} or GND	3.6 V			±5	μA
		V _I = 0.58 V	1.65 V	25			
		V _I = 1.07 V	1.65 V	-25			
		V _I = 0.7 V	2.3 V	45			
ll(hold)		V _I = 1.7 V	2.3 V	-45			μA
		V _I = 0.8 V	3 V	75			
		V ₁ = 2 V	3 V	-75			
		V _I = 0 to 3.6 V [‡]	3.6 V			±500	
loz		V _O = V _{CC} or GND	3.6 V			±10	μA
ICC		$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	3.6 V			10	μA
∆ICC		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 3.6 V			750	μA
Ci	Control inputs Data inputs	VI = V _{CC} or GND	3.3 V		5 6		pF
Co	Outputs	$V_{O} = V_{CC}$ or GND	3.3 V	<u> </u>	7.5		pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
[‡] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

		V _{CC} = ± 0.1	1.8 V 5 V	V _{CC} = ± 0.2		V _{CC} =	$V_{CC} = 2.7 \text{ V}$ $V_{CC} = 3.3 \pm 0.3 \text{ V}$		3.3 V 3 V	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency				100		100		150	MHz
tw	Pulse duration, CLK high or low	3.8		3.3		3.3		3.3		ns
t _{su}	Setup time, data before CLK [↑]	3		1.8		2.1		1.8		ns
t _h	Hold time, data after CLK↑	1		0.5		0.5		0.5		ns



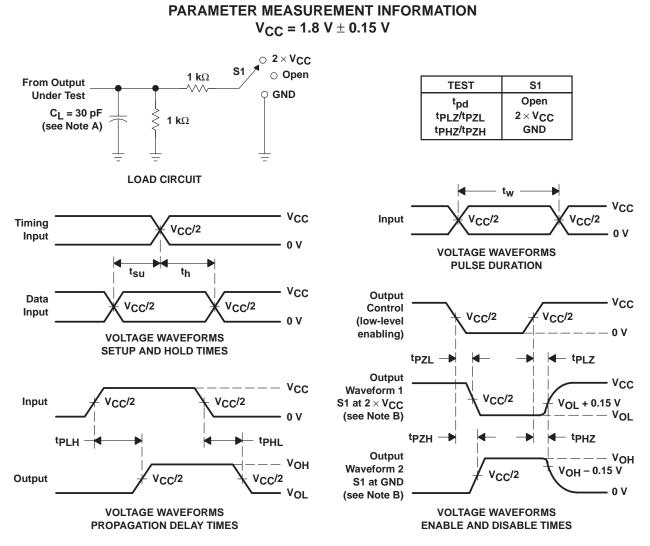
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		(001101)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fmax					100		100		150		MHz
^t pd	CLK	Q	1.5	6.4	1	3.9		3.6	1.1	3.6	ns
t _{en}	OE	Q	3.6	8.1	2.1	5.6		5.3	1.6	5.2	ns
^t dis	OE	Q	2.7	7.9	0.9	4.5		4.4	1.2	4.5	ns

operating characteristics, $T_A = 25^{\circ}C$

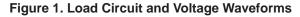
PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT	
				TYP	TYP	TYP	ÖNIT
	Power dissipation capacitance	Outputs enabled	C _I = 0. f = 10 MHz	44	46	50	рF
C _{pd}	per flip-flop	Outputs disabled	$C_{L} = 0$, $f = 10 MHz$	24	26	29.5	рг



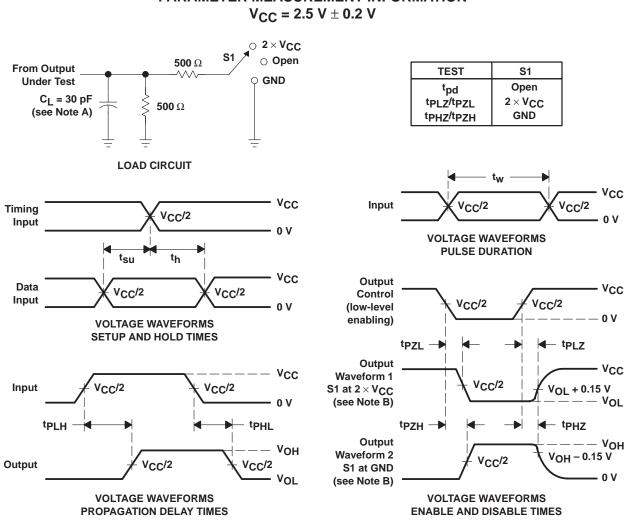


NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2 ns, t_f \leq 2 ns. D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpzL and tpzH are the same as ten.
- G. tPLH and tPHL are the same as tpd.







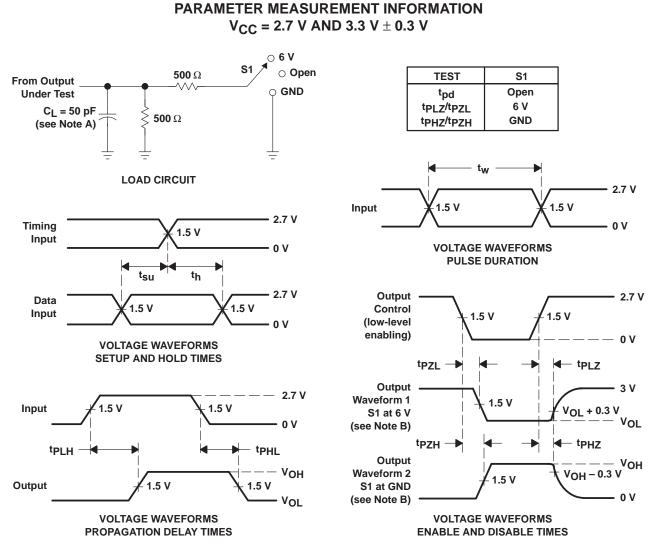
PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

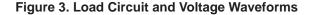
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2 ns, t_f \leq 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpzL and tpzH are the same as ten.
- G. tPLH and tPHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms





- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_f ≤ 2.5 ns, t_f ≤ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .





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